

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re application : Wushing Yin, et al.
 Application No. : 10/636,105
 Filed : August 7, 2003
 Confirmation No. : 9143
 For : INTEGRATED UNDERFILL PROCESS FOR BUMPED CHIP
 ASSEMBLY
 Attorney's Docket : INDUM-110XX

TC Art Unit: 3726

 I hereby certify that this correspondence is being deposited with the
 United States Postal Service as first class mail in an envelope
 addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA
 22313-1450 on 11-12-2003.

By: 

Victor B. Lebovici
 Registration No. 30,846
 Attorney for Applicants

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Sir:

It is desired to cite for the record in this application the enclosed references listed on the attached copy of PTO Form #1449. The paragraph(s) marked below are applicable to this Information Disclosure Statement.

[] (1) Pursuant to 37 C.F.R. § 1.97(b)(1) and (2), the attached Information Disclosure Statement is being filed within three months of the filing date of the above identified national application or within three months of the date of entry of the national stage as set forth in 37 C.F.R. § 1.491 of the above identified application. Accordingly, applicant(s) believes that no fee or statement under 37 C.F.R. § 1.97(e) is required.

[X] (2) Pursuant to 37 C.F.R. § 1.97(b)(3), applicant(s) believes the attached Information Disclosure Statement is being filed before the mailing date of a first Office action on the merits. Accordingly, applicant(s) believes that no fee or statement under 37 C.F.R. § 1.97(e) is required.

[] (3) Pursuant to 37 C.F.R. § 1.97(b)(4), applicant(s) believes the attached Information Disclosure Statement is being filed before the mailing date of a first Office action after the filing of a request for continued examination under § 1.114. Accordingly, applicant(s) believes that no fee or statement under 37 C.F.R. § 1.97(e) is required.

[] (4) Pursuant to 37 C.F.R. § 1.97(c), the attached Information Disclosure Statement is being filed before the mailing date of a final action or a notice of allowance and is accompanied by:

[] a statement under 37 CFR § 1.97(e); or

[] the fee set forth in § 1.17(p).

PETITION UNDER 37 CFR § 1.97(d)

[] (5) Pursuant to 37 CFR § 1.97(d), applicant(s) hereby petitions the Commissioner to consider the attached Information Disclosure Statement which is being filed on or before payment of the issue fee. This petition is accompanied by a statement under 37 C.F.R. § 1.97(e) and the petition fee set forth in 37 C.F.R. § 1.17(p).

STATEMENT UNDER 37 C.F.R. § 1.97(e)(1)

[] (6) The undersigned hereby states that each item of information contained in the attached Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement.

STATEMENT UNDER 37 C.F.R. § 1.97(e)(2)

[] (7) The undersigned hereby states that no item of information contained in the attached Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application and, to the knowledge of the

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undersigned after making reasonable inquiry, no item of information contained in the attached Information Disclosure Statement was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of this Information Disclosure Statement.

The filing of this Information Disclosure Statement is not a representation by the undersigned as to personal knowledge of the contents of every word or phrase of the material enclosed or that reliance on other suitably trained professionals has not been made.

If a search report of a searching agency is enclosed identifying the nature of the relevance of each document, such a designation is deemed to satisfy 37 C.F.R. § 1.98(a)(3) even if in a foreign language because the codes are the same in all languages. However, applicant(s) does not necessarily adopt the position reflected by that report.

The Commissioner is hereby authorized to charge payment of any additional fees associated with this communication or credit any overpayment to Deposit Account No. 23-0804. Triplicate copies of this letter are enclosed.

Respectfully submitted,

WUSHING YIN, ET AL.

By:

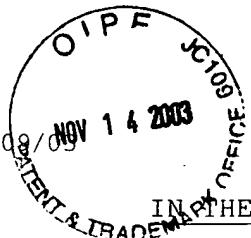


Victor B. Lebovici
Registration No. 30,864
Attorney for Applicants

WEINGARTEN, SCHURGIN,
GAGNEBIN & LEOVICI LLP
Ten Post Office Square
Boston, Massachusetts 02109

Telephone: (617) 542-2290
Telecopier: (617) 451-0313

Enclosure
298205



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PATENT

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STATEMENT UNDER 37 C.F.R. § 1.97(e)(1)

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Victor B. Lebovici
Registration No. 30,864
Attorney for Applicants

WEINGARTEN, SCHURGIN,
GAGNEBIN & LEBOVICI LLP
Ten Post Office Square
Boston, Massachusetts 02109

Telephone: (617) 542-2290
Telecopier: (617) 451-0313

Enclosure
298205

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Page 1 of 2

(REV. 05/03)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE			ATTY. DOCKET NO. INDUM-110XX	APPLICATION NO. 10/636,105	
 INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>			APPLICANT: Wushing Yin, et al.			
			FILING DATE 8/7/03	TC ART UNIT 3726		
U.S. PATENT DOCUMENTS						
EXAMINER INITIAL	DOCUMENT NUMBER	PUBLICATION/ ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE
	US2003/0096452	5/22/2003	Yin, et al.	438	108	
	US2003/0096453	5/22/2003	Wang, et al.	438	108	
	US2003/0109080	6/12/2003	Dias	438	108	
	US5,128,746	7/7/1992	Pennisi, et al.	357	72	
	US6,038,136	3/14/2000	Weber	361	783	
	US6,157,086	12/5/2000	Weber	257	788	
	US6,168,972	1/2/2001	Wang, et al.	438	108	
	US6,457,828	11/5/2002	Hoang	438	108	
	US6,506,681	1/14/2003	Grigg, et al.	438	692	
FOREIGN PATENT DOCUMENTS						
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
	WO 99/56312	11/4/1999	WIPO			X
OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, etc.)						
	Product Data Sheet; "Epoxy Flip Chip Flux PK-001"; Indium Corporation of America					
	Product Data Sheet; "Pb-Free Epoxy Flip Chip Flux PK-002"; Indium Corporation of America					
	Surface Mount Technology; Materials, Processes and Equipment; Carmen Capillo; Unisys Corporation; San Jose, CA					
EXAMINER			DATE CONSIDERED			
*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.						

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	US					
	US					
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	US					
	US					
	US					
	US					
FOREIGN PATENT DOCUMENTS						
.	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
.						
OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, etc.)						
	"No Flow Underfill Reliability is Here - Finally?"; Michael A. Previti; Cookson Semiconductor Packaging Materials; Alpharetta, GA					
	"The Development of No-Flow Underfill Materials for Flip-Chip Applications"; Dr. C. P. Wong; S. H. Shi; School of Materials Science and Engineering & Packaging Research Center; Georgia Institute of Technology; February 2, 1999					
	"No-Flow Underfill Materials for Environment Sensitive Flip-Chip Process; A Dissertation Presented to The Academic Faculty; Zhuqing Zhang; Georgia Institute for Technology; June 2001Chi Flfor					
	"A Novel Approach to Incorporate Silica Filler into No-Flow Underfill"; Zhuqing Zhang, Jicum Lu; C. P. Wong; School of Materials Science and Engineering and Packaging Research Center; Georgia Institute of Technology; Georgia; Pages 1-7					
EXAMINER			DATE CONSIDERED			
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